



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Sectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2015-05-11</b>
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>Patrizia Santoro</b>	<b>Representative Title</b>	<b>IPD MD Champion</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
------------------------------	-------------	----------------------------	-----------------

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STB36NF06LT4	TLD2*EL6CA62	A	SHENZHEN B/E	2015-05-11
Amount	UoM	Unit type	ST ECOPACK Grade	
1401.00	mg	Each	ECOPACK1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2, 9.15, 4.5	2	GULL WING	
Comment	Package: D2 PACK	MD valid for CP:STB36NF06LT4		

QueryList : ROHS directive 2011/65/EU \_ July 2011

Query		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
5 - Product(s) is obsolete, no information is available		false
6 - Product(s) is unknown, no information is available		false
Exemption Id.	Description	
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)	

QueryList : REACH-17th December 2014

Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TLD2*EL6CA62					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	3.384	mg	supplier	die	Silicon (Si)	7440-21-3		3.273	mg	967199	2336
				supplier	metallization	Aluminium (Al)	7429-90-5		0.064	mg	18913	46
				supplier	Passivation	Silicon Oxide	7631-86-9		0.018	mg	5319	13
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	591	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.005	mg	1478	4
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.022	mg	6501	16
Leadframe	Copper & its alloys	779.567	mg	supplier	alloy	Copper (Cu)	7440-50-8		777.537	mg	997396	554987
				supplier	alloy	Iron (Fe)	7439-89-6		0.358	mg	459	256
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.654	mg	839	467
				supplier	metallization	Nickel (Ni)	7440-02-0		1.012	mg	1298	722
				supplier	metallization	Phosphorus (P)	12185-10-3		0.006	mg	8	4
Soft solder	Solder	3.291	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.143	mg	955029	2243
				supplier	solder	Silver (Ag)	7440-22-4		0.082	mg	24916	59
				supplier	solder	Tin (Sn)	7440-31-5		0.066	mg	20055	47
Bonding wires	Other inorganic materials	1.349		supplier	wire	Aluminium (Al)	7429-90-5		1.348	mg	999259	962
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	741	1
Encapsulation	Other Organic Materials	610.920	mg	supplier	mold compound	Silica, vitreous	60676-86-0		492.402	mg	806001	351465
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		42.764	mg	69999	30524
				supplier	mold compound	Phenol resin	9003-35-4		24.437	mg	40000	17443
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		36.655	mg	60000	26163
				supplier	mold compound	Antimony Trioxide	1309-64-4		7.331	mg	12000	5233
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		4.276	mg	6999	3052
				supplier	mold compound	Carbon black	1333-86-4		3.055	mg	5001	2181
connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1777